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MECHANIC BGA reballing stencil 4D-X grooved with leakproof for iPhone X

Product ID: 22898

Price: **18.00 EUR**

Product weight: **0.30 kg**

Description:

MECHANIC BGA reballing stencil 4D-X grooved with leakproof for iPhone X the stepped grooves can quickly adjust the tin sweating location of IC beads, the square hole position makes the tin bead form easier to remove.

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